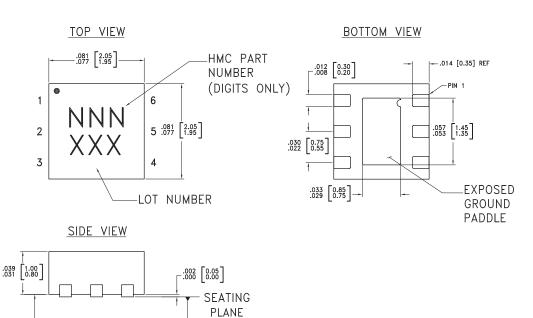


## LP2 (E) - 2 x 2 mm DUAL FLATPACK NO-LEAD (DFN) PLASTIC PACKAGE



### LP2 (E) Package Outline Drawing

△ .003[0.08]|C



-C-

#### NOTES:

- 1. LEADFRAME MATERIAL: COPPER ALLOY
- 2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
- 3. PAD SPACING TOLERANCE IS NON-CUMULATIVE
- PAD BURR LENGTH SHALL BE 0.15mm MAXIMUM.
  PAD BURR HEIGHT SHALL BE 0.05mm MAXIMUM.
- 5. PACKAGE WARP SHALL NOT EXCEED 0.05mm.
- 6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
- REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED LAND PATTERN.

## Package Information

Part Number Suffix	Package Body Material	Lead Finish	MSL Rating	Package Marking [3][4]
LP2	RoHS Compliant Mold Compound	Sn/Pb Solder	MSL1 [1]	NNN XXX
LP2E	RoHS Compliant Mold Compound	100% matte Sn	MSL1 [2]	NNN XXX

- [1] Max peak reflow temperature of 235  $^{\circ}\text{C}$
- [2] Max peak reflow temperature of 260 °C
- [3] 4-Digit lot number XXXX
- [4] 3-Digit part number NNN

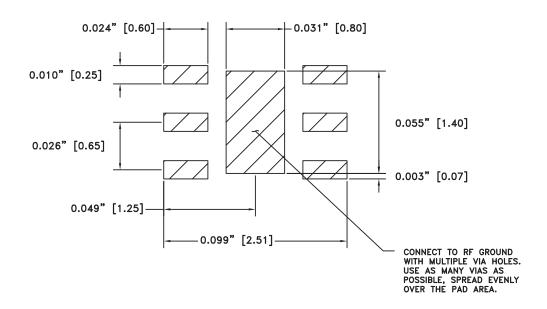


# LP2 (E) - 2 x 2 mm DUAL FLATPACK NO-LEAD (DFN) PLASTIC PACKAGE



### Suggested LP2 (E) PCB Land Pattern





### NOTES:

- 1. DIMENSIONS ARE IN INCHES [MILLIMETERS].
- 2. PAD WIDTH SHOWN IS FOR SOLDERING ONLY. BEYOND SOLDERING AREA ALL CONDUCTORS THAT CARRY RF AND MICROWAVE SIGNALS SHOULD HAVE 50 OHM CHARACTERISTIC IMPEDANCE.
- 3. SOLDERMASK ON FAR SIDE SHOULD TENT OR PLUG VIA HOLES.